

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-25 (canceled)

26. (currently amended) A chip package method for checking an electronic package, comprising:

a semiconductor chip having a bottom surface with a mark used to be read by a code reader; and

a first bump on said bottom surface.

~~providing said electronic package with a mark; and~~

~~reading said mark using a laser code reader.~~

27. (currently amended) The chip package method of claim 26, wherein said mark comprises a bar code.

28. (currently amended) The chip package method of claim 26, wherein said mark comprises an identity for a product.

29. (currently amended) The chip package method of claim 26 further comprising a protecting structure on said mark and on said bottom surface not covered by said mark. ;  
~~wherein said mark comprises an identity for a manufacturer.~~

30. (currently amended) The chip package method of claim 26 further comprising a second bump on said bottom surface, wherein said mark is between said first and second bumps. ;  
~~wherein said electronic package comprises a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said mark, said protecting structure being over said mark, wherein said mark is visible through said protecting structure.~~

31. (currently amended) The chip package method of claim 26-30 further comprising a protecting structure on said mark, wherein said protecting structure is non-black. ;~~wherein said surface further comprises multiple pads.~~

32. (currently amended) The chip package method of claim 26-30 further comprising a protecting structure on said mark. ;~~wherein said semiconductor chip has another surface with multiple pads.~~

33. (currently amended) A semiconductor chip having a top surface with a mark used to be read by a code reader and a bottom surface with multiple pads.

~~An electronic package comprising a mark read by a laser code reader.~~

34. (currently amended) The semiconductor chip ~~electronic package~~ of claim 33, wherein said mark comprises a bar code.

35. (currently amended) The semiconductor chip ~~electronic package~~ of claim 33, wherein said mark comprises an identity for a product.

36. (currently amended) The semiconductor chip ~~electronic package~~ of claim 33, wherein said mark comprises an identity for a manufacturer.

37. (currently amended) The semiconductor chip ~~electronic package~~ of claim 33 further comprising multiple bumps on said multiple pads. ~~a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said mark, said protecting structure being over said mark, wherein said mark is visible through said protecting structure.~~

38. (currently amended) A chip package comprising:

\_\_\_\_\_ a substrate;

\_\_\_\_\_ a semiconductor chip over said substrate;

\_\_\_\_\_ a wirebonded wire connecting said semiconductor chip and said substrate; and

\_\_\_\_\_ a protecting structure over said semiconductor chip and said substrate, and enclosing said wirebonded wire, wherein said semiconductor chip is visible through said protecting structure.

~~A semiconductor chip having a surface with a mark read by a laser code reader.~~

39. (currently amended) The chip package semiconductor chip of claim 38, wherein said semiconductor chip has a mark used to be read by a code reader, wherein said mark is visible through said protecting structure. ~~mark comprises a bar code.~~

40. (currently amended) The chip package semiconductor chip of claim ~~39, 38,~~ wherein said mark comprises an identity for a product.

41. (currently amended) The chip package semiconductor chip of claim ~~39, 38,~~ wherein said mark comprises a bar code. ~~an identity for a manufacturer.~~

42. (currently amended) The chip package semiconductor chip of claim 38 comprising multiple balls under said substrate. ~~, wherein said surface further comprises multiple pads.~~

43. (currently amended) The chip package semiconductor chip of claim 38, wherein said substrate is flexible. ~~semiconductor chip has another surface with multiple pads.~~

44. (currently amended) ~~An electronic~~ A chip package comprising:

\_\_\_\_\_ a substrate;

\_\_\_\_\_ a semiconductor chip over said substrate;

\_\_\_\_\_ multiple bumps between said semiconductor chip and said substrate; and

\_\_\_\_\_ a protecting structure over said semiconductor chip and said substrate, wherein said semiconductor chip is visible through said protecting structure.

~~—— a semiconductor chip having a first surface with multiple pads and a second surface with a mark; and~~

~~—— a protecting structure over said mark, wherein said mark is visible through said protecting structure.~~

45. (currently amended) The chip electronic package of claim 44, wherein said semiconductor chip has a top surface with a mark used to be read by a code reader and covered by said protecting structure, and a bottom surface having said multiple bumps formed thereon, wherein said mark is visible through said protecting structure. ~~; wherein said mark comprises a bar code.~~

46. (currently amended) The chip electronic package of claim 45, 44, wherein said mark comprises a bar code. ~~number.~~

47. (currently amended) The chip electronic package of claim 45, 44, wherein said mark comprises an identity for a product.

48. (currently amended) The chip electronic package of claim 44 further comprising an underfill material between said semiconductor chip and said substrate, and enclosing said multiple bumps. ~~; wherein said mark comprises an identity for a manufacturer.~~

49. (currently amended) The chip electronic package of claim 47-44 further comprising multiple balls under said substrate. ~~; wherein said mark is colored.~~

50. (currently amended) A device ~~An electronic package comprising:~~

\_\_\_\_\_ a semiconductor chip having a top surface having a first region with a mark and a second region without said mark; and

\_\_\_\_\_ a protecting structure over said mark and said second region, wherein said mark is visible through said protecting structure.

~~\_\_\_\_\_ a semiconductor chip having a surface with a mark comprising a number, a bar code, or an identity for a product or a manufacturer; and~~

~~\_\_\_\_\_ a protecting structure over said mark, wherein said mark is visible through said protecting structure.~~

51. (currently amended) The device semiconductor chip of claim 50, wherein said mark comprises a bar code. ~~, wherein said surface further comprises multiple pads.~~

52. (currently amended) The device semiconductor chip of claim 50, wherein said semiconductor chip has a bottom ~~another~~ surface with multiple pads.